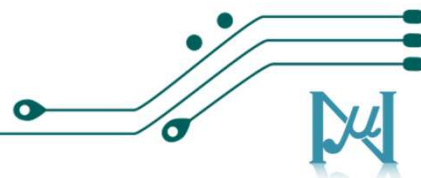
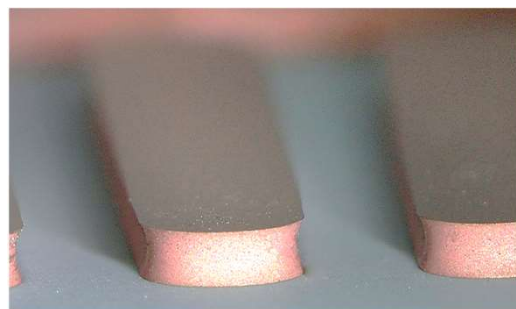


PCB for Power semiconductor devices



Ultra Thick Copper circuit for high current PCB used in power semiconductor devices and coils.

By accuracy etching method by our own patented facilities and our original etching method, we enable to narrow the pitch of patterns than regular etching method. High current PCB is now more compact and high density. Prevent temperature rise using metal core or high heat dissipation or heat-resistant materials.



Comparison of etching minimum in the same copper thickness

Regular etching method					Our standard etching method				Our innovative etching method NEW			
Cu thickness (mm)	Line (mm)		Gap (mm)	Pitch: P (mm)	Line (mm)		Gap (mm)	Pitch: P (mm)	Line (mm)		Gap (mm)	Pitch: P (mm)
	Top : T	Bottom : B	Bottom : b		Top : T	Bottom : B	Bottom : b		Top : T	Bottom : B	Bottom : b	
0.5	0.70	1.10	0.80	1.90	0.50	0.75	0.70	1.45	0.50	0.50	0.50	1.00
0.8	0.70	1.30	1.20	2.50	0.60	1.00	0.80	1.80	0.60	0.60	0.60	1.20
1.0	—	—	—	—	0.70	1.20	0.90	2.10	0.70	0.70	0.70	1.40

※Regular etching data is reference. ※We can advice suitable specifications for your request.

Examples Of usage

Power semiconductor devices, High current coil PCB, LED, Power electronics, Hybrid car, Power control unit of motor in EV



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